

N and P-Channel Enhancement Mode Power MOSFET

Description

The NCE30NP07S uses advanced trench technology to provide excellent $R_{\text{DS}(\text{ON})}$ and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

General Features

N-Channel

 $V_{DS} = 30V, I_{D} = 6.5A$

 $R_{DS(ON)}$ < 24m Ω @ V_{GS} =10V

 $R_{DS(ON)}$ < 37m Ω @ V_{GS} =4.5V

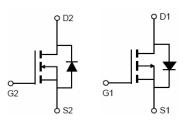
P-Channel

 $V_{DS} = -30V, I_{D} = -7A$

 $R_{DS(ON)}$ < 32m Ω @ V_{GS} =-10V

 $R_{DS(ON)}$ < 70m Ω @ V_{GS} =-4.5V

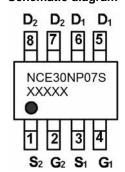
- High power and current handing capability
- Lead free product is acquired
- Surface mount package



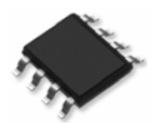
N-channel

P-channel

Schematic diagram



Marking and pin assignment



SOP-8 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE30NP07S	NCE30NP07S	SOP-8	Ø330mm	12mm	4000 units

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Param	Symbol	N-Channel	hannel P-Channel		
Drain-Source Voltage	V_{DS}	30	-30 ±20	V	
Gate-Source Voltage		V _{GS}		±20	V
Continuous Duoin Current	T _A =25℃		6.5	-7	А
Continuous Drain Current	T _A =70°C	I _D	5.4	-5.8	
Pulsed Drain Current (Note 1)	,	I _{DM}	30	-30	Α
Maximum Power Dissipation	T _A =25℃	P _D	2.0	2.0	W
Operating Junction and Storage	Temperature Range	T_{J} , T_{STG}	-55 To 150	-55 To 150	$^{\circ}$

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note2)	$R_{\theta JA}$	N-Ch	62.5	°C/W
Thermal Resistance, Junction-to-Ambient (Note2)	$R_{\theta JA}$	P-Ch	62.5	°C/W

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N-CH Electrical Characteristics (T_A=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30	33	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	1	1.6	3	V
Drain Course On State Decistance	В	V _{GS} =10V, I _D =6A	-	19	24	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =6A	-	26	37	mΩ
Forward Transconductance	g fs	V _{DS} =5V,I _D =6A	15	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ -45\/\/ -0\/	-	485.8	-	PF
Output Capacitance	Coss	$V_{DS}=15V, V_{GS}=0V,$	-	65.2	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	54	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	4.0	-	nS
Turn-on Rise Time	t _r	V_{DD} =15V, R_L =2.5 Ω	-	2.0	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{GEN} =3 Ω	-	14.0	-	nS
Turn-Off Fall Time	t _f		-	3.0	-	nS
Total Gate Charge	Qg	\/ 45\/ L CA	-	12.6	-	nC
Gate-Source Charge	Q _{gs}	$V_{DS}=15V,I_{D}=6A,$	-	1.9	-	nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	2.6	-	nC
Drain-Source Diode Characteristics	,		•	•		
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =6A	-	0.8	1.2	V

NCE30NP07S

P-CH Electrical Characteristics (T_A=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV _{DSS}	V_{GS} =0 V I_D =-250 μ A	-30	-33	-	٧	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V,V _{GS} =0V	-	-	-1	μA	
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA	
On Characteristics (Note 3)							
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=-250\mu A$	-1.3	-1.65	-2.5	V	
Drain-Source On-State Resistance	В	V _{GS} =-10V, I _D =-6.5A	-	28	32	mΩ	
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-6.5A	-	49	70	mΩ	
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-6.5A	10	-	-	S	
Dynamic Characteristics (Note4)				•			
Input Capacitance	C _{lss}	\/ 45\/\/ 0\/	-	691.9	-	PF	
Output Capacitance	C _{oss}	V _{DS} =-15V,V _{GS} =0V, F=1.0MHz	-	113.7	-	PF	
Reverse Transfer Capacitance	C _{rss}	F=1.UIVIFIZ	-	109.4	-	PF	
Switching Characteristics (Note 4)				•			
Turn-on Delay Time	t _{d(on)}		-	7.5	-	nS	
Turn-on Rise Time	t _r	V_{DD} =-15V, R_L =2.3 Ω	-	5.5	-	nS	
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10 V , R_{GEN} =6 Ω	-	19	-	nS	
Turn-Off Fall Time	t _f		-	7	-	nS	
Total Gate Charge	Qg	\/ - 45\/ - 0.50	-	16.3	-	nC	
Gate-Source Charge	Q _{gs}	V_{DS} =-15V, I_{D} =-6.5A V_{GS} =-10V	-	2.2	-	nC	
Gate-Drain Charge	Q _{gd}	V _{GS} =-1UV	-	4.1	-	nC	
Drain-Source Diode Characteristics							
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-6.5A	-	-	-1.2	V	

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production



N- Channel Typical Electrical and Thermal Characteristics (Curves)

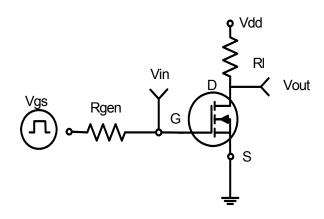


Figure 1:Switching Test Circuit

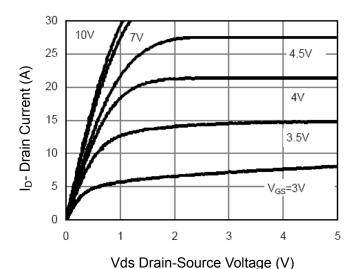


Figure 3 Output Characteristics

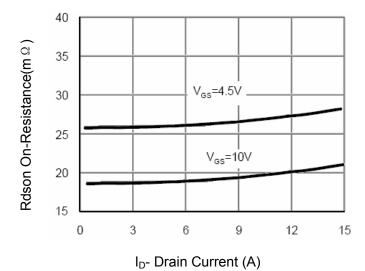


Figure 5 Drain-Source On-Resistance

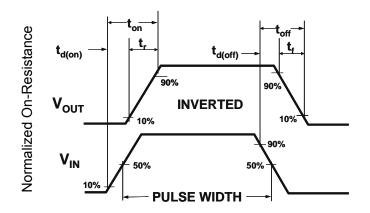


Figure 2:Switching Waveforms

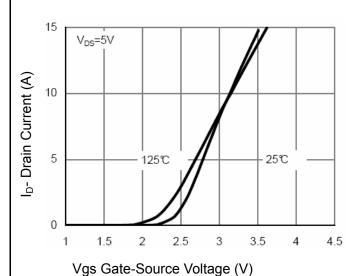


Figure 4 Transfer Characteristics

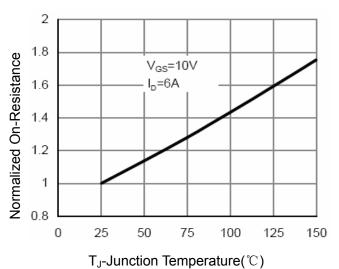


Figure 6 Drain-Source On-Resistance



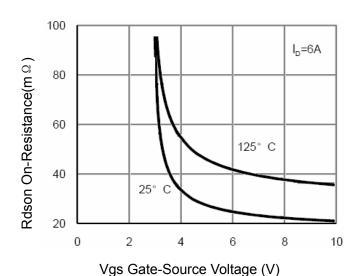


Figure7 Rdson vs Vgs

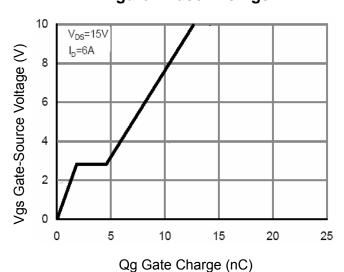


Figure 9 Gate Charge

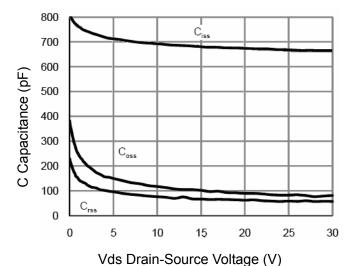
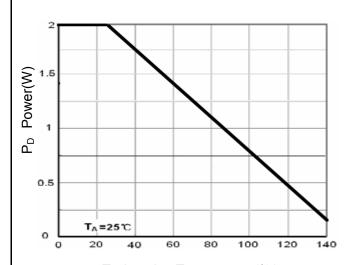


Figure 11 Capacitance vs Vds



 T_J -Junction Temperature($^{\circ}$ C) Figure 8 Power Dissipation

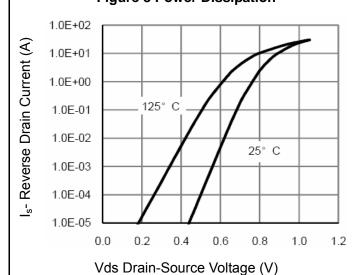
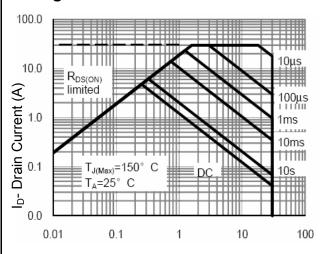


Figure 10 Source- Drain Diode Forward



Vds Drain-Source Voltage (V)
Figure 12 Safe Operation Area



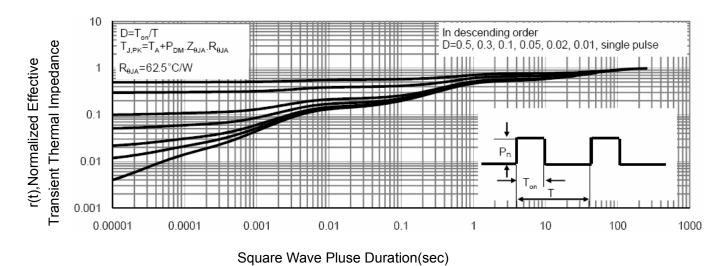


Figure 13 Normalized Maximum Transient Thermal Impedance



P- Channel Typical Electrical and Thermal Characteristics (Curves)

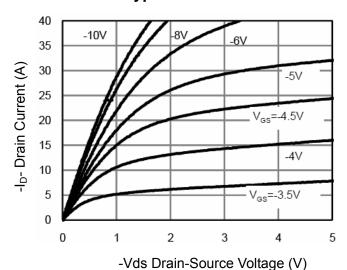


Figure 1 Output Characteristics

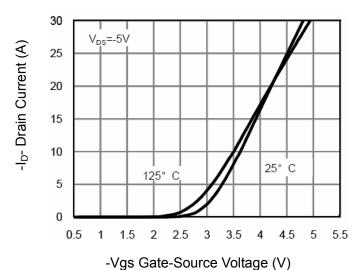


Figure 2 Transfer Characteristics

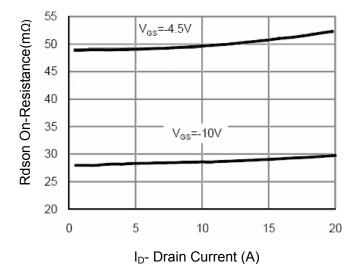


Figure 3 Rdson- Drain Current

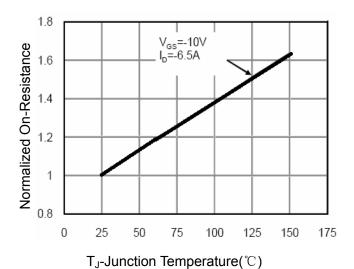


Figure 4 Rdson-Junction Temperature

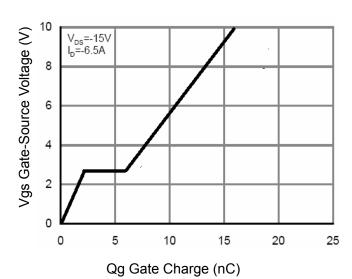


Figure 5 Gate Charge

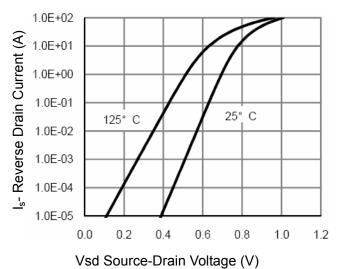


Figure 6 Source- Drain Diode Forward



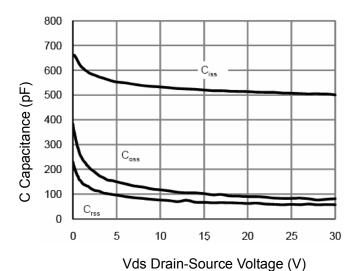
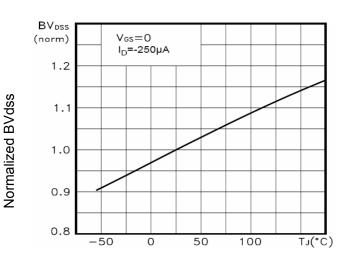


Figure 7 Capacitance vs Vds



 T_J -Junction Temperature (°C) Figure 9 BV_{DSS} vs Junction Temperature

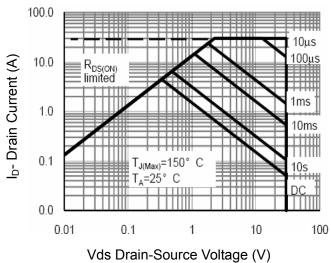


Figure 8 Safe Operation Area

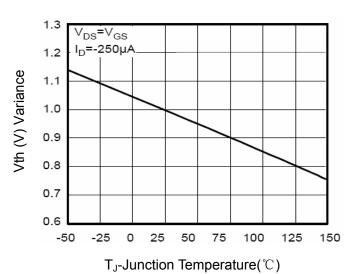
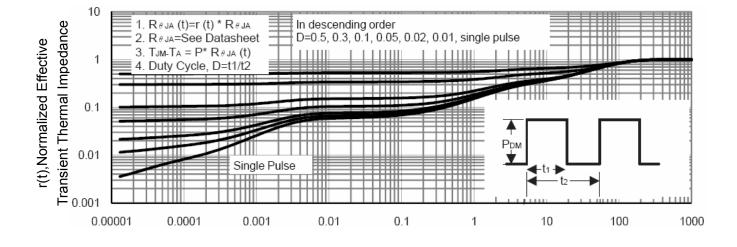


Figure 10 V_{GS(th)} vs Junction Temperature

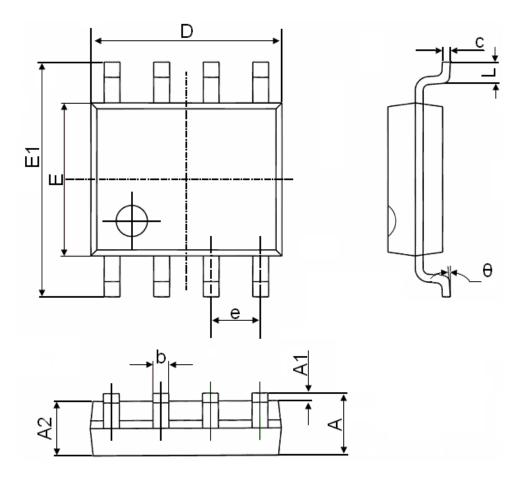


Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance



SOP-8 Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270	(BSC)	0.050	(BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	

NCE30NP07S

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